

Electronic Patent Application Fee Transmittal

Application Number:	10018188			
Filing Date:	18-Dec-2001			
Title of Invention:	Abrasive compound for cmp, method for polishing substrate and method for manufacturing semiconductor device using the same, and additive for cmp abrasive compound			
First Named Inventor/Applicant Name:	Naoyuki Koyama			
Filer:	William Ivan Solomon/Kelli Harris			
Attorney Docket Number:	511.40998X00			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120